To: Mannix, John[mannixj@monroe.wednet.edu]
Cc: Piplic, Devlin[piplicd@monroe.wednet.edu]; Ramanauskas, Peter[ramanauskas.peter@epa.gov]; Moore, Kendall[moore.kendall@epa.gov]; Peachey, Robert[peachey.robert@epa.gov]; Skadowski, Suzanne[Skadowski.Suzanne@epa.gov]; Bernard, Nancy (DOH)[Nancy.Bernard@doh.wa.gov]; Amanda Zych[azych@snohd.org]; Jeff Ketchel[jketchel@snohd.org]
From: Mullin, Michelle
Sent: Thur 6/9/2016 9:24:23 PM
Subject: Epoxy PCB encapsulant research

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Hello Mr. Mannix-

I wanted to get back with you regarding your question about EPA research on encapsulant products.

The EPA Office of Research and Development (ORD) complete research on this topic in 2010. In general, epoxy coatings that were tested had the best performance in the research.

Here is a link to the research fact sheet on encapsulation:
https://www.epa.gov/sites/production/files/2015-08/documents/pcb_encapsulation_fs.pdf

Here is a link the research report with more details:
https://www.epa.gov/sites/production/files/2015-08/documents/p100fa5l.pdf

You can see on pages 8 and 13 of the report that "Epoxy- no solvent" performed the best of the three tested epoxies. The "Epoxy- low VOC" performed the most poorly of the three epoxies, which was still significantly better than the other sealants tested.

For best performance to control migration of PCBs, the no-solvent Epoxy is recommended.

Please let me know if you have any further questions.

Sincerely,

Michelle Mullin

PCB Coordinator

US EPA Region 10

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